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Abstract

The present invention relates to a wafer cutting machine 1 comprising two rotatable work spindles 1, 2 arranged in coaxial fashion relative to each other, each carrying on the end thereof a separating disk 3, 4 supported on a hub 5, 6, and each being movable relative to a work table 8 adapted to be equipped with a wafer 7, characterized in that the two separating disks 3, 4 are each arranged to face one another, each of the hubs 5, 6 being positioned on the back side of the separating disk 3, 4 and arranged on the work spindle 1, 2.

(Figure 3)